

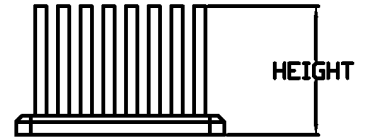
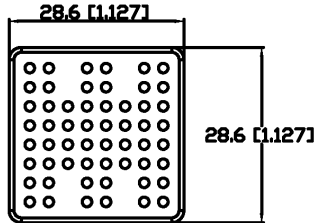
Model : CMBA022929 Series



BGA Heat Sink Specification

For 29x29 Chip set

- Material : Al 6063
- Dimension :
Foot print : 29x29mm
Height : 12,15,18,21,23,28,33 mm
Base (thickness) : 2.6mm



- Finish: Black Anodize
- Chip set package thickness and clip color
3.3+/-0.25mm - Yellow clip
1.7+/-0.25mm - Blue clip
0.8+/-0.25mm - Orange clip
- Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : T710 or others



Performance

Heat Source (LxW)	15x15
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